

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
.	12.0	+3.0/-3.0	PLATED	469
▪	12.0	+3.0/-3.0	PLATED	211
•	12.1	+3.0/-3.0	PLATED	156
◦	35.0	+3.0/-3.0	PLATED	150
◦	40.0	+3.0/-3.0	PLATED	26
◦	42.0	+3.0/-3.0	PLATED	10
△	55.0	+3.0/-3.0	PLATED	20
○	128.5	+2.0/-1.0	NON-PLATED	2
○	152.0	+2.0/-2.0	NON-PLATED	3
□	156.0	+2.0/-2.0	NON-PLATED	3

FABRICATION NOTES

- 1) MATERIAL SELECTION:370HR
PER LATEST REVISION OF IPC-4011 (OR EQUIVALENT) UL RECOGNIZED ZPVM P2 MIN. 130C FLAME CLASS V-0 OR BETTER,MINIMUM CTI RATING OF 175, 0.062 +/- 0.007 THICK MATERIAL PER IPC-4101..
2 OZ COPPER FOR ALL LAYERS. SOLDERABLE SURFACE TO BE ENIG(ELECTROLESS NICKEL IMMERSION GOLD).
- 2) SOLDERMASK: THE USE OF SOLDERMASK COATING SHALL BE IN ACCORDANCE WITH THE REQUIREMENTS OF IPC-SM-840. ALL SOLDERABLE SURFACES ARE TO BE FREE OF SOLDERMASK. COLOR GREEN.
- 3) SILKSCREEN: USE WHITE NON-CONDUCTIVE INK. ALL COMPONENTS AND TESTPOINTS LANDS ARE TO BE FREE OF INK.
- 4) MANUFACTURER'S IDENTIFICATION: ADD IN ETCH OR TO SILKSCREEN.
- 5) ELECTRICAL TEST BARE BOARD TEST REQUIRED.
- 6) DRILL SIZES ARE FINISHED SIZE AFTER PLATING.
- 7) FABRICATE TO MEET EU Rohs DIRECTIVE.
- 8) COPPER THIEVING OF THE SIGNAL LAYERS IS NOT ALLOWED, SPACING TO ANY EXISTING BOARD FEATURE TO BE 0.060 MINIMUM.
- 9) PCB MUST HAVE UL 94V-0 AND CTI RATINGS MARKED ON ONE SIDE.
- 10) FABRICATE IN ACCORDANCE WITH IPC-A-600 OR IPC-6012 LATEST REVISION CLASS 2.
- 11) MAX WARP AND TWIST NOT TO EXCEED 0.010 PER LINEAR INCH.
- 12) DIMENSION TOL: XX +/-0.010 : XXX +/-0.005.
- 13) MIN ANNULAR RING 0.003 MIN PLATED HOLE WALL THICKNESS 0.001.
14. ALL (156) 12.1 DIAMETER HOLES TO BE PLUGGED FROM THE TOP SIDE (COMPONENT SIDE) WITH EITHER UV OR THERMALLY CURED PLUGGING MATERIAL. THE PLUGGING MATERIAL SHOULD NOT DRIP OUT THE BOTTOM SIDE OF THE PCB.

TENNANT CO. Q25066-PCB REV E FABRICATION DRAWING

